Special Issue

Nano-materials Based 3D Electronics

Message from the Guest Editor

As Moore's law is going to hit the wall imposed by quantum effects, the further miniaturization of microelectronic systems is expected to be driven by 3D heterogeneous integration. In order to realize high-density and high-performance integration in a 3D fashion, stacking chips in the vertical direction is a key step. To enable communication among stacked chips, new materials and semiconductor processes have to be developed. In this perspective, nano-materials have attracted a great deal of attention due to their special electrical, mechanical, thermal and chemical properties. In addition, high density integration of components in microsystems places the challenging-enough thermal management problem on fire. In this Special Issue of Electronics, we would like to report on the most recent progresses in 3D integration of microsystems. Contributions on all dimensions of 3D integration are welcome.

Guest Editor

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Deadline for manuscript submissions

closed (31 August 2018)

Electronics

an Open Access Journal by MDPI

Impact Factor 2.6
CiteScore 6.1

mdpi.com/si/11058

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Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

Editor-in-Chief

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